



Tongfu Microelectronics Co., Ltd (TFME) as a  
Subcontractor for Assembly of 144L LQFP  
Copper Wire Package

Zilog, Inc.  
1590 Buckeye Drive  
Milpitas, CA 95035-7418

November 14, 2022

Subject: Tongfu Microelectronics Co., Ltd (TFME) as a Subcontractor for the  
Assembly of 144L LQFP Copper Wire package

Dear Valued Customer and/or Distributor:

To better serve our customers, Zilog has qualified Tongfu Microelectronics Co.,  
Ltd (TFME) as packaging subcontractor for the assembly of 144L LQFP copper  
wire using our standard qualification process (please see the attached  
qualification data). Please also note that TFME is an existing qualified Zilog  
package subcontractor for other package styles.

Should you have questions on this matter or need additional assistance, please  
contact [MCUService@littelfuse.com](mailto:MCUService@littelfuse.com)

Thank you for your continued interest in Zilog products and services.

Sincerely,

Alan Shaw  
Senior Manager MCU Operations  
Zilog-a Littelfuse Company



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RELIABILITY TEST DATA:	REJ/SS
WIRE PULL	0/32
BALL SHEAR	0/32
DIE SHEAR	0/5
EXTERNAL VISUAL	0/125
SOLDERABILITY	0/6
PACKAGE DIMENSION	0/5
PRECONDITIONING (30°C, 60%RH, 192 HRS)	0/135
PRESSURE POT (121°C, 100%RH, 2 ATM, 168 HRS)	0/45
TEMPERATURE CYCLE (-65°C, 150°C, 500X)	0/43
UUBIASED HAST, 96 HRS	0/45
HTS (150°C, 168 HRS)	0/77
ZILOG QUALIFICATION REPORT	22112680